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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Chen *et al.* **Examiner:** Stacy Whitmore

Serial No.: 10/711,418 **Art Unit:** 2825

Filed: 09/17/2004 **Confirmation No.:** 5417

Title: NON-DESTRUCTIVE EVALUATION OF MICROSTRUCTURE AND INTERFACE

ROUGHNESS OF ELECTRICALLY CONDUCTING LINES IN SEMICONDUCTOR

INTEGRATED CIRCUITS IN DEEP SUB-MICRON REGIME

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450 Washington D.C. 20231

RESPONSE TO THE INTERVIEW SUMMARY OF DECEMBER 15, 2006

In response to the December 15, 2006 telephonic interview between Examiner Stacy A. Whitmore and Khoi Nguyen, the applicant's representative states that the Examiner's *Interview Summary* accurately reflects the substance of the interview.

Date: January 4, 2007

/Jack P. Friedman/ Jack P. Friedman

Registration No.: 44,688

For

Khoi D. Nguyen

Registration No.: 47,820

Customer No: 30449 Schmeiser, Olsen & Watts 22 Century Hill Drive, Suite 302

Latham, NY 12110

Telephone: (518) 220-1850 Fax: (518) 220-1857